SPECIAL-PURPOSE

Fully-Automatic Multifunction Wafer Mounter-Peeler

RAD-2510F/12Sa

- Ultra-thin wafer mounting & peeling
- Built-in BG-Tape peeling unit
- Advanced inline pre-cut system
- DBG™ process capability

LINTEC Corporation

BENEFITS

Multi-functional wafer-mounter: ideal for manufacturing ultra-thin wafers

Our multifunctional wafer-mounter is ideal for processing of ultra-thin wafers. After back-grinding, the subsequent processes of UV-irradiation, alignment, frame-mounting, and peeling of BG-tape are performed in one single equipment.

In-line compatible with backgrinding systems for DBG™(Dicing Before Grinding) processes

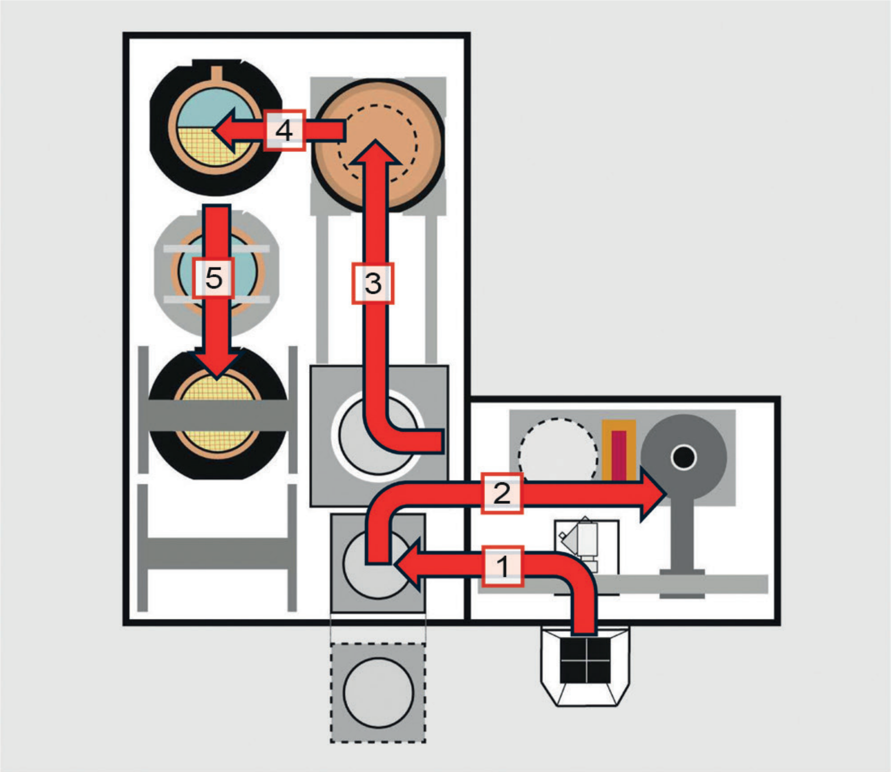
Supports in-line operation with *DISCO's DFG8000* and *DGP8000* series for advanced thin-chip dicing. Minimizes wafer contamination by reducing the wafer-handling steps from 4 times in a stand-alone tool to 2 times with an inline backgrinding system.

✂ Advanced inline pre-cut system

Minimizes waste of material, decreases production cost and reduces tape pitch from 10mm to 2mm.

All-in-one mounter/peeler solution

MOUNTER-PEELER PROCESS-FLOW



1 The wafer with BG-tape is taken from loadport and is aligned

2 The transfer-arm moves the wafer to the UV-irradiation unit

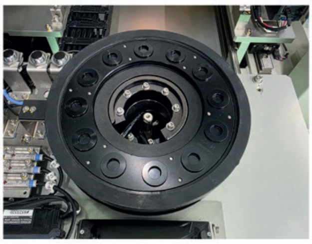
3 The wafer is transferred to the dicing-tape attachment-table for mounting onto a ringframe

4 The wafer is moved to the peeling-table to remove the BG-tape

5 The finished workpiece is unloaded

BERNOULLI HANDLING SYSTEM

Robot-endeffector*



Alignment table*

LINTEC's market-proven soft-contact Bernoulli handling technology can be integrated into the robot end-effector, the alignment table, and the wafer transfer-arm.

This exceptionally gentle handling method is designed to minimize contact with the wafer after BG tape removal.

*Reference pictures only

SPECIFICATION

Applicable Frame Sizes	**Standard:** ø300: SEMI Standard ø200: DTF2-8-1 **Option:** ø150: DTF2-6-1
Loading Specs	**Standard for single-loader:** FOSB (12“) Double-slot cassette (12“) DBG cassette (12“) Open cassette (8“) **Options:** Open cassette (6“) In-line specification with backgrinder
Anti-ESD Specification	**Standard:** ±100V or less within 10sec after the end of operation* *Data obtained under LINTEC‘s measurement conditions **Option:** ±50V or less immediately after the end of operation** **Reference value, measured on mirror wafer
UPH	45 wafers/hour* *UPH measured under the condition of standard spec and ø300mm full thickness wafer.
UV-irradiation	UV source for BG-tape irradiation can be pre-set in accordance to customers requirements

STANDARD

- Handling of 300mm / 200mm wafers
- Single load port for FOUP/ FOSB or cassette
- Attachment-table heater function for superior mounting quality
- Built-in BG-tape peeling unit
- Built-in UV-irradiation unit with automated UV intensity control
- Anti-ESD specification:
  ±100V or less within 10sec after the end of operation

OPTIONS

- Handling of 150mm wafers
- Double-pitch slot wafer cassette
- Inline pre-cut unit
- Compatible with *DISCO Corporation's* Inline equipment series *DFG8000* and *DGP8000*
- Wafer-ID reading function
- Bernoulli Handling System (wafers without BG-tape)
- DBG™ process capability, incl. circle-shaped robot-endeffector, porous alignment-table and camera-alignment
- Table-cleaning function for alignment-table, attachment-table, peeling-table
- Host communication function (SECS/GEM)
- Vision system (wafer-ID reader & barcode attachment system)

Adwill

Tape × Equipment

Contact us.
We look forward to meeting you!

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